

Directly heated negative temperature coefficient thermistors —

Part 2: Sectional specification — Surface mount negative temperature coefficient thermistors

ICS 31.040.30

National foreword

This British Standard is the UK implementation of EN 60539-2:2004+A1:2010. It is identical to IEC 60539-2:2003, incorporating amendment 1:2010. It supersedes BS EN 60539-2:2004 which is withdrawn.

The start and finish of text introduced or altered by amendment is indicated in the text by tags. Tags indicating changes to IEC text carry the number of the IEC amendment. For example, text altered by IEC amendment A1 is indicated by **A1** **A1**.

The UK participation in its preparation was entrusted to Technical Committee EPL/40X, Capacitors and resistors for electronic equipment.

A list of organizations represented on this committee can be obtained on request to its secretary.

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**Directly heated negative temperature coefficient thermistors
Part 2: Sectional specification -
Surface mount negative temperature coefficient thermistors
(IEC 60539-2:2003)**

Thermistors à coefficient de température négatif à chauffage direct
Partie 2: Spécification intermédiaire -
Montage en surface de thermistors à coefficient de température négatif
(CEI 60539-2:2003)

Direkt geheizte temperaturabhängige Widerstände mit negativem Temperaturkoeffizienten
Teil 2: Rahmenspezifikation -
Oberflächenmontierbare temperaturabhängige Widerstände mit negativem Temperaturkoeffizienten
(IEC 60539-2:2003)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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BS EN 60539-2:2004+A1:2010
EN 60539-2:2004+A1:2010 (E)

Foreword

The text of document 40/1346/FDIS, future edition 1 of IEC 60539-2, prepared by IEC TC 40, Capacitors and resistors for electronic equipment, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60539-2 on 2004-02-01.

The following dates were fixed:

- latest date by which the EN has to be implemented
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- latest date by which the national standards conflicting
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Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60539-2:2003 was approved by CENELEC as a European Standard without any modification.

Foreword to amendment A1

The text of document 40/2034/CDV, future amendment 1 to IEC 60539-2:2003, prepared by IEC TC 40, Capacitors and resistors for electronic equipment, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as amendment A1 to EN 60539-2:2004 on 2010-09-01.

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- latest date by which the national standards conflicting
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Annex ZA has been added by CENELEC.

Endorsement notice

The text of amendment 1:2010 to the International Standard IEC 60539-2:2003 was approved by CENELEC as an amendment to the European Standard without any modification.

Annex ZA
(normative)**Normative references to international publications
with their corresponding European publications**

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
<i>Replace the reference:</i>				
IEC 60068-2-58	1999	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	1999
<i>with the following:</i>				
IEC 60068-2-58	2004	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58 + corr. December	2004 2004

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